

E
CON

wherein said circuit board includes at least two grooves defined by said conductive pattern, and located approximate to one of said bonding areas to put the bonding area therebetween, and wherein said at least two grooves do not extend into said board main body.

Please add new Claims 19-26, as follows:

E2
19. (New) A chip part device comprising:

a circuit board including a board main body and a conductive layer formed on said board main body, said conductive layer having a plurality of bonding areas defined by a conductive pattern; and

a chip element mounted on said circuit board, and having a plurality of bump electrodes which are joined with said bonding areas by ultrasonic bonding,

wherein said circuit board includes at least two grooves defined by said conductive pattern and located approximate to one of said bonding areas to put the bonding area therebetween, and wherein at least one of said grooves does not electrically isolate said conductive pattern.

20. (New) A chip part device as claimed in claim 19, wherein said groove is formed extending in a direction traversing an ultrasonically vibrating direction of the ultrasonic bonding.

21. (New) A chip part device as claimed in claim 19, wherein said at least two grooves is provided in said conductive layer as at least one of an isolated notch part and a recess located proximate to and not extending within said one of said bonding areas, wherein said notch part or recess partially narrows said conductive pattern to form a narrow pattern part.

22. (New) A chip part device comprising:

a circuit board including a board main body and a conductive layer formed on said board main body, said conductive layer having a plurality of bonding areas defined by a conductive pattern; and

*EQ
(64F)*
a chip element mounted on said circuit board, and having a plurality of bump electrodes which are joined with said bonding areas by ultrasonic bonding,

wherein said circuit board includes means for evenly distributing ultrasonic energy applied in a vibrating direction to said plurality of bump electrodes and said plurality of bonding areas.

23. (New) A chip part device as claimed in claim 22, wherein said means for distributing ultrasonic energy comprises at least two grooves defined by said conductive pattern and located approximate to one of said bonding areas to put the bonding area therebetween, and wherein at least one of said grooves does not electrically isolate said conductive pattern.

24. (New) A chip part device as claimed in claim 22, wherein said means for evenly distributing ultrasonic energy comprises at least two grooves defined by said conductive pattern and located approximate to one of said bonding areas to put the bonding area therebetween, and wherein said at least two grooves do not extend into said board main body.

25. (New) A chip part device as claimed in claim 24, wherein said groove is formed extending in a direction traversing an ultrasonically vibrating direction of the ultrasonic bonding.

26. (New) A chip part device as claimed in claim 24, wherein said at least two grooves is provided in said conductive layer as at least one of an isolated notch part and a recess located proximate to and not extending within said one of said bonding areas, wherein said notch part or recess partially narrows said conductive pattern to form a narrow pattern part.